

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC010N04LST	**Issued**	2. August 2019
MA#	MA005345711		
Package	PG-TDSON-8-48	**Weight***	109.11 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.517	1.39	1.39	13906	13906
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		131	
	non noble metal	zinc	7440-66-6	0.057	0.05		525	
	non noble metal	iron	7439-89-6	1.145	1.05		10495	
	non noble metal	copper	7440-50-8	46.496	42.61	43.72	426136	437287
wire	noble metal	gold	7440-57-5	0.041	0.04	0.04	377	377
encapsulation	organic material	carbon black	1333-86-4	0.082	0.08		755	
	plastics	epoxy resin	-	3.787	3.47		34709	
	inorganic material	silicondioxide	60676-86-0	37.295	34.18	37.73	341807	377271
leadfinish	non noble metal	tin	7440-31-5	1.264	1.16	1.16	11582	11582
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	266	266
solder	noble metal	silver	7440-22-4	0.052	0.05		472	
	non noble metal	tin	7440-31-5	0.103	0.09		945	
	non noble metal	lead	7439-92-1	1.907	1.75	1.89	17482	18899
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.00		42	
	non noble metal	zinc	7440-66-6	0.018	0.02		169	
	non noble metal	iron	7439-89-6	0.368	0.34		3370	
	non noble metal	copper	7440-50-8	14.930	13.68	14.04	136831	140412
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com